



BOARD CHARACTERISTICS

Copper Layer Count:	6	Board Thickness:	1.6000 mm
Board overall dimensions:	78.0000 mm x 138.0000 mm	Min hole diameter:	0.2000 mm
Min track/spacing:	0.2032 mm / 0.2032 mm	Impedance Control:	No
Copper Finish:	Immersion gold	Plated Board Edge:	No
Castellated pads:	No		
Edge card connectors:	No		

NOTES:

D101–D108 are mounted upside–down.
 Assemble with leaded solder.
 Fabricate on polyimide.
 2oz outer, 2oz inner copper.

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Sheet:
 File: backplane.kicad_pcb

Title: backplane

Size: A Date: 2022-05-11
 KiCad E.D.A. kicad 7.0.1

Rev: C
 Id: 1/1

